

Title (en)  
APPARATUS AND METHOD FOR CUTTING AND CHAMFERING A MATERIAL

Title (de)  
VORRICHTUNG UND VERFAHREN ZUM TRENNEN UND ABFASEN EINES MATERIALS

Title (fr)  
APPAREIL ET PROCÉDÉ DE COUPE ET DE CHANFREINAGE DE MATÉRIAU

Publication  
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Application  
**EP 21807005 A 20211103**

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Abstract (en)  
[origin: WO2022128242A1] The invention relates to a method for cutting and chamfering a workpiece (1) containing a transparent material, wherein material modifications (5) are introduced into the transparent material of the workpiece (1) along a cutting line (4) by means of ultrashort laser pulses of an ultrashort pulse laser (2), whereupon the material of the workpiece (1) is cut, in a cutting step, along the material modification area (50) formed thereby, the laser pulses being applied to the workpiece (1) at an angle of attack ( $\alpha$ ), and the material modifications (5) being modifications of type 1 and/or type II that are associated with a change in the refractive index of the material of the workpiece (1).

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See references of WO 2022128242A1

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